

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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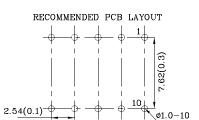
9.9mm (0.39") SINGLE DIGIT NUMERIC DISPLAY

Features

- Low power consumption
- ullet Robust package
- I.C. Compatible
- \bullet Standard configuration: Gray face w/ white segments
- \bullet Optional black face provides superior color contrast
- RoHS Compliant







Notes:

- 1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25 (0.01")$ unless otherwise noted.
- 2. Specifications are subject to change without notice.

7.62(0.3)

Absolute Maximum Ratings (T _A =25°C)		UG (GaP)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	I_{F}	25	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	140	mA	
Power Dissipation	P_{D}	62.5	mW	
Operating Temperature	T_{A}	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85	-0	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds			

Operating Characteristics (T _A =25°C)	UG (GaP)	Unit	
Forward Voltage (Typ.) (I _F =10mA)	V_{F}	2	V
Forward Voltage (Max.) (I _F =10mA)	V_{F}	2.5	V
Reverse Current (Max.) (V _R =5V)	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λΡ	565*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λD	568*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	$\triangle \lambda$	30	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	pF

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Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (I _F =10mA) ucd		Wavelength CIE127-2007* nm λP	Description
			min.	typ.		
XDUG08A	Green	GaP	2200 900*	6390 2290*	565*	Common Anode , Rt.Hand Decimal.

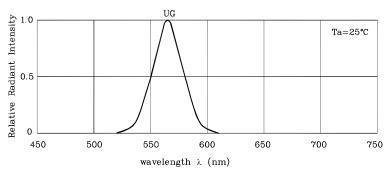
^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Jan 17,2014

XDSA0143 V7-X Layout: Maggie L.

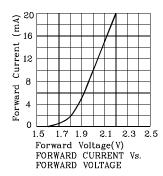


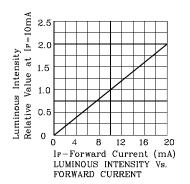


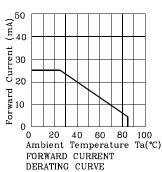


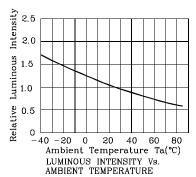
RELATIVE INTENSITY Vs. CIE WAVELENGTH

♦ UG

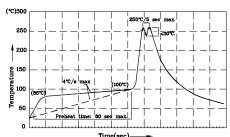








Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



- nmend pre-heat temperature of 105°C or less (as measured with a noccouple attached to the LED pins) prior to immersion in the solder with a maximum solder bath temperature of 250°C wave soldering temperature between 245°C \sim 255°C for 3 sec (5 sec
- 2.Peak wave soldering temperature netwernax).
 3.Do not apply stress to the epoxy resin A-Pixtures should not incur stress on the during soldering process.
 5.SAC 305 solder alloy is recommended.
 6.No more than one wave soldering pass.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

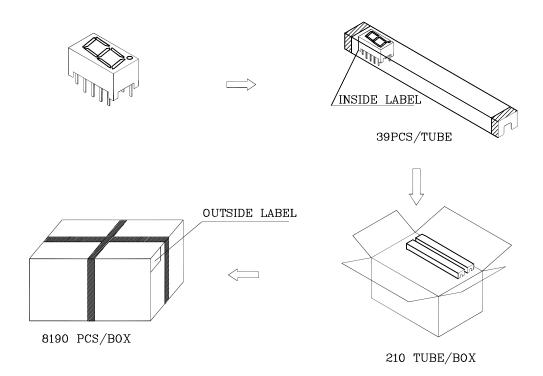
- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.





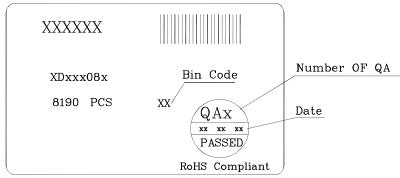
PACKING & LABEL SPECIFICATIONS



Inside Label On IC-tube



Outside Label On Box



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